

SDS-Single

“DRY” TYPE POU ABATEMENT

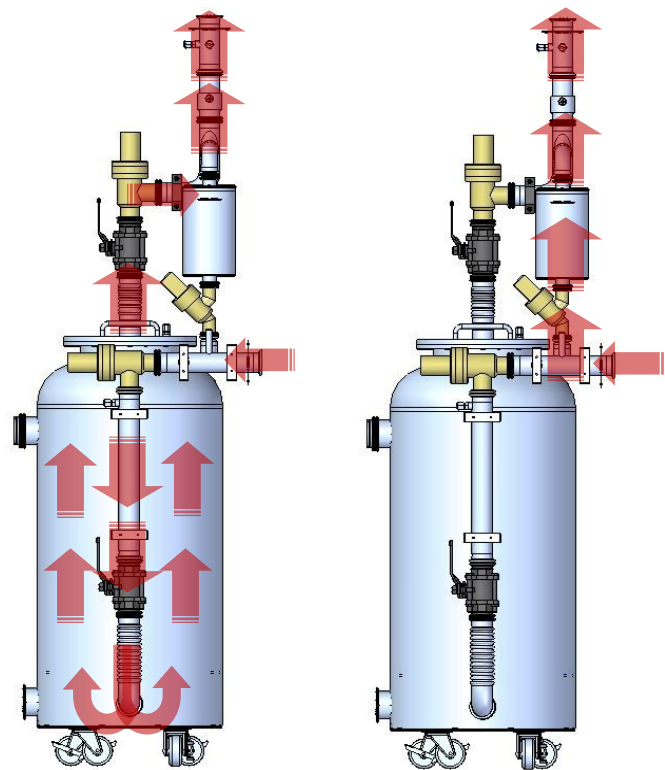
Exhaust solution for high-volume semiconductor manufacturing



Benefits

- > Virtually zero unscheduled downtime with bypass cartridge
- > High abatement efficiency
- > Designed for target gas emissions level below TLV
- > Low overall CoO
- > HVM (high volume manufacturing) proven

System Specifications



Normal Operation

Bypass Operation

Applications

- > Semiconductor processes

Features

- > Primary 80 liter cartridge
- > Bypass mini-cartridge
- > Double-acting pneumatic valves for power failure ride through
- > Main cartridge temperature interlock
- > 80% detect - color change sight tube
- > N2 eductor standard / blower option for inlet pressure control
- > Gas monitoring options
- > In-situ oxidation option

- Total System Capacity: **150 slm**
- MTBF: **>8,300 hours**
- MTTR: **<4 hour**
- MTTP: **<3 hour**

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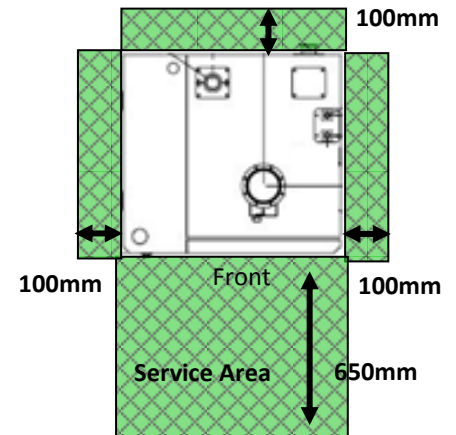
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Dimensions and Weight

SDS-Single

Dimension (W x D x H in mm)	650 x 540 x 1650
Weight (kg)	250



Utilities

Item	Type	Typical Usage	Connection Type
Electricity	208VAC 1 Phase	0.1 KW	5A service
N2	3 ~ 6 kg/cm ²	40 LPM	¼" SS compression
Air or N2	5 ~ 6.5 kg/cm ²	<0.1 LPM	¼" SS compression (Valve Operation)
Gas Exhaust	-50 ~ -100 mmH2O	0.2 m ³ /min	KF40 Flange
Cabinet Exhaust	-50 ~ -60 mmH2O	1 m ³ /min	Ø100mm

Dry Media

Application	Adsorbent	Target Gas	Specific Gravity
Etch	C1	Cl2, BCl3, HBr, HCl, HF, F2	0.70
Diffusion	3-2	SiH4, SiCl2H2, B2H6	0.80
	M1	NH3, VOC	0.75
Implant	5	PH3, AsH3, B2H6, GeH4	0.80
	6	BF3, GeF4	0.70

- A combination of dry media may be used for optimum abatement efficiency and lifetime
- Other dry media types available

Environment

- Clean and dry environment
- Temperature: 5 ~ 27 °C
- Relative Humidity: < 55%